[WeA1] Nanoscale Thin Film Deposition III	
Session Date	November 12 (Wed.), 2025
Session Time	09:00-10:40
Session Room	Room A (Capri Room, 2F)

[WeA1-1] [Invited] 09:00-09:30

Non-Fluorinated Molybdenum Metallization in 3D NAND

Jungho Lee (Lam Research Korea, Korea)

[WeA1-2] [Invited] 09:30-10:00

Atomic Layer Deposition of Molybdenum Thin Films: Enhancing Deposition Characteristics and Film Quality with Advanced Deposition Materials

Changbong Yeon and Jaesun Jung (Soulbrain Co., Ltd., Korea)

[WeA1-3] 10:00-10:20

Interlayer Engineering for Reliable Hybrid Channel NAND Flash

Taewon Hwang, So Young Lim, and Jin-Seong Park (Hanyang Univ., Korea)

[WeA1-4] 10:20-10:40

Atomic Layer Deposition of Binary Alloy Thin Films for Advanced Interconnects

Yeong-Seo Cho, Myung-Jin Jung, and Se-Hun Kwon (Pusan Nat'l Univ., Korea)